IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity.

Please amend the claims as follows:

1. (Twice Amended) A testing apparatus for a wafer of semiconductor dice comprising:

a first rigid support member for receiving a plurality of semiconductor dice in wafer form having a predetermined orientation, the first rigid support member having a plurality of contact members thereon and having a plurality of electrical connectors connected to the contact members for establishing communication with test circuitry;

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a second rigid support member for selectively engaging the first rigid support member to retain the plurality of semiconductor dice in wafer form therebetween, one of the first rigid support member and the second rigid support member including a single cavity for retaining said plurality of semiconductor dice in wafer form therein during testing; and

a single biasing assembly including a single floating platform of a preselected area substantially sized for the single cavity, the single biasing assembly mounted to one of the first rigid support member and second rigid support member, the single biasing assembly sized for uniformly biasing the plurality of semiconductor dice in wafer form against the contact members.

2. The apparatus as claimed in claim 1, wherein the plurality of semiconductor dice comprises a wafer.

3. The apparatus as claimed in claim 1, wherein the plurality of semiconductor dice comprises a die cluster in wafer form.

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4. The apparatus as claimed in claim 1, wherein the single biasing assembly comprises the single floating platform in contact with an elastomeric polymer member.

5. The apparatus as claimed in claim 1, further comprising aligning devices for aligning the first rigid support member with the second rigid support member.

6. (Twice Amended) A wafer testing apparatus comprising:

a first rigid support member and a second rigid support member for receiving a plurality of semiconductor dice on a wafer therebetween, one of the first rigid support member and second rigid support member including a single cavity for retaining said plurality of semiconductor dice on a wafer therein during testing;

a plurality of contact members formed on the first rigid support member for communicating with electrical connectors for connecting to external test circuitry;

a single biasing assembly including a single floating platform having a preselected area substantially sized to correspond with the single cavity and an elastomeric member disposed on the second rigid support member, the single biasing assembly sized for uniformly biasing said plurality of semiconductor dice on a wafer towards the contact members, the single floating platform directly supporting the wafer with the elastomeric member sandwiched between the single floating platform and the second rigid support member.

7. The apparatus as claimed in claim 6, further comprising an alignment device for aligning the first rigid support member and the second rigid support member with one another.

8. (Previously Amended) The apparatus as claimed in claim 6, further comprising an alignment device including a dowel on one of the first rigid support member and second rigid

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support member and a corresponding opening on the other of the first rigid support member and the second rigid support member.

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